

L Number	Hits	Search Text	DB	Time stamp
1	81	374/6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:27
2	2563	374/6.ccls. or 165/47.ccls. or 165/53.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:44
3	957	(374/6.ccls. or 165/47.ccls. or 165/53.ccls.) and (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:45
4	2862	374/6.ccls. or 165/47.ccls. or 165/53.ccls. or 165/9.3.ccls. or 165/9.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:55
5	1032	(374/6.ccls. or 165/47.ccls. or 165/53.ccls. or 165/9.3.ccls. or 165/9.1.ccls.) and (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:45
6	50	((374/6.ccls. or 165/47.ccls. or 165/53.ccls. or 165/9.3.ccls. or 165/9.1.ccls.) and (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) and ((stress or strain) with (heat or thermal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:45
7	825	165/53.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:55
8	38	165/53.ccls. and method.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:56
-	8727	118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:23
-	8044	137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:41
-	2285	141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:41
-	457	261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:41
-	2576	261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:41

-	7031	261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:41
-	28468	(118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:41
-	4715	(wafer or substrate) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas)) and ((heat or thermal) with (stress or strain)) not (((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas) same (stress or strain))) or (((("6197151") or ("6123775") or ("6079356") or ("5997649") or ("5968276") or ("5882411") or ("5846332") or ("5844205") or ("5647911") or ("5614026") or ("5582866") or ("5567243") or ("5439524") or ("4854263")).PN.) or (((("6050216") or ("5882411") or ("5846332") or ("5778713") or ("5667631") or ("5597439") or ("5569356") or ("5472565") or ("5262029") or ("5074456") or ("4612077") or ("4585920") or ("4547247")).PN.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:42
-	5330	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) same (heat or thermal) with (stress or strain))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 13:07
-	7391	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) with (stress or strain) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:42
-	7391	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and ((heat or thermal) with (stress or strain)) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:42
-	3198	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:42

27811	(wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:42
8469	((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:43
2802	((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:43
3889	((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:43
2160	((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and ((heat or thermal) same (stress or strain) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:43
2117	((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and ((heat or thermal) same (stress or strain) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma))) or blood)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:43

1607	(((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and ((heat or thermal) same (stress or strain)) and plasma not (((wafer or substrate) and ((("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ((("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or blood)) and semiconductor us-20020069968-\$-did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
2		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
70	((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) and (stress or strain) and plasma not ((wafer or substrate) and ((("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) and (427/446.ccls. or 427/457.ccls. or 29/746.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
14	("6197151") or ("6123775") or ("6079356") or ("5997649") or ("5968276") or ("5882411") or ("5846332") or ("5844205") or ("5647911") or ("5614026") or ("5582866") or ("5567243") or ("5439524") or ("4854263").PN.	USPAT	2004/01/05 12:44
2	6170432.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
73	((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas) same (stress or strain))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
13	((("6050216") or ("5882411") or ("5846332") or ("5778713") or ("5667631") or ("5597439") or ("5569356") or ("5472565") or ("5262029") or ("5074456") or ("4612077") or ("4585920") or ("4547247").PN.	USPAT	2004/01/05 12:44
4	"6,170,432"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44

294	(wafer or substrate) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas)) same ((heat or thermal) with (stress or strain))) not (((118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42.ccls. or 261/62-63.ccls.) or (261/64.1.ccls. or 261/65.ccls. or 261/75-76.ccls. or 261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)) and (((injector or nozzle or sprayer or port or jet or "shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with gas) same (stress or strain))) or (((("6197151") or ("6123775") or ("6079356") or ("5997649") or ("5968276") or ("5882411") or ("5846332") or ("5844205") or ("5647911") or ("5614026") or ("5582866") or ("5567243") or ("5439524") or ("4854263").PN.) or (((("6050216") or ("5882411") or ("5846332") or ("5778713") or ("5667631") or ("5597439") or ("5569356") or ("5472565") or ("5262029") or ("5074456") or ("4612077") or ("4585920") or ("4547247").PN.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
107	(wafer or substrate) and (("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) same (heat or thermal) with (stress or strain)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
180	(wafer or substrate) and (("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
101	(((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:44
879	(((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal) same (stress or strain)) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma)) and semiconductor) and ((expand\$3 or expansion) with (heat or thermal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 13:01
2	6477980.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:45

47	(((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and ((heat or thermal) same (stress or strain)) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or blood)) and semiconductor) and ((expand\$3 or expansion) with (heat or thermal))) and (expand and contract)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 12:46
52	(((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and ((heat or thermal) same (stress or strain)) and plasma and (expand and contract) not (((((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and (heat or thermal) same (stress or strain)) and plasma not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or (((wafer or substrate) same (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule)) same ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3)) and (heat or thermal).clm. and (stress or strain).clm. and plasma not ((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (stress or strain)).clm. and plasma) or blood)) and semiconductor) and ((expand\$3 or expansion) with (heat or thermal))) and (expand and contract)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 13:02
2246	((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (bracket or shelf))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 15:30
550	((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (bracket or shelf)) and (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule) same (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 13:12
1	"4113577".PN.	USPAT	2004/01/05 14:32
1	"4469566".PN.	USPAT	2004/01/05 14:32
1	"5683564".PN.	USPAT	2004/01/05 14:32
1	"6080288".PN.	USPAT	2004/01/05 14:33
1	"6103085".PN.	USPAT	2004/01/05 14:33
0	((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (bracket or shelf)) not (((wafer or substrate) and ("shower head" or grid or showerhead or diffus\$3 or baffle or permeat\$3 or dispers\$3 or mix\$3 or distribut\$3) with (bracket or shelf)) and (reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule) same (wafer or substrate)) and 29/525.02.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 15:31
5997	((reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule) same (wafer or substrate)) and (29/\$.ccls. or 73/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 15:33

-	53	(((reactor or chamber or vessel or tank or station or hous\$3 or encase\$4 or container or ampoule) same (wafer or substrate)) and (29/\$.ccls. or 73/\$.ccls.)) and ((stress and strain) with (thermal or heat))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 15:35
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